uClamp0511PQ µClamp® 1-Line ESD protection

PROTECTION PRODUCTS - MicroClamp®

Description

The μ Clamp® series of TVS arrays are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace multilayer varistors (MLVs) in portable applications. They feature large cross-sectional area junctions for conducting high transient currents and offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The μ Clamp®0511PQ is in a 2-pin, SLP1006P2 package. It measures 1.0 x 0.6 x 0.5mm. The leads are spaced at a pitch of 0.65mm and are finished with lead-free NiPdAu. Each device will protect one bidirectional line operating at ± 5 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (± 15 kV air, ± 8 kV contact discharge) and higher. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players. The uClamp0511PQ is qualified to AEC-Q100 Grade 1 for Automotive use.

Features

- ◆ Transient protection for data lines to IEC 61000-4-2 (ESD) ±30kV (air and contact) IEC 61000-4-4 (EFT) 40A (tp = 5/50ns) Cable Discharge Event (CDE)
- ◆ Ultra-small package (1.0 x 0.6 x 0.5mm)
- Protects one I/O or power line
- Low clamping voltage
- Working voltage: 5V
- Low leakage current
- Solid-state silicon-avalanche technology
- ◆ AEC-Q100 Grade 1 Qualified

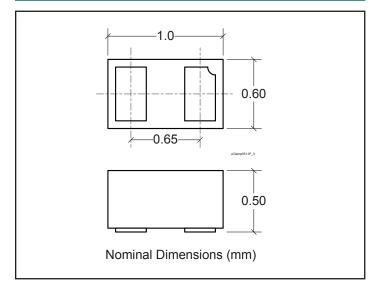
Mechanical Characteristics

- SLP1006P2 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- Lead Finish: NiPdAu
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant

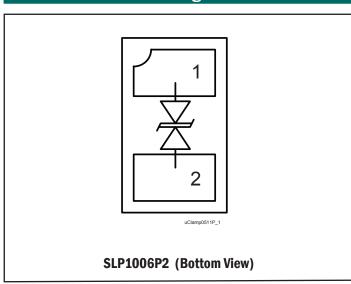
Applications

- Cellular Handsets & Accessories
- Cordless Phones
- Smart Phones
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- MP3 Players
- Automotive Applications

Package Dimensions



Schematic & Pin Configuration





Absolute Maximum Ratings

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P _{pk}	170	Watts
Peak Pulse Current (tp = 8/20μs)	I _{PP}	12	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	± 30 ± 30	kV
Operating Temperature	T,	-40 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

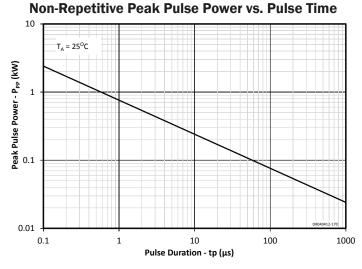
Electrical Characteristics (T=25°C unless otherwise specified)

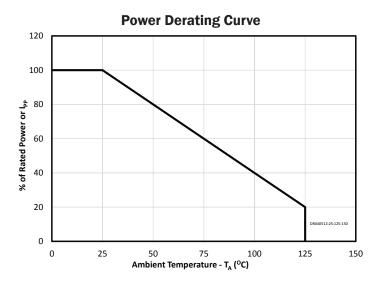
Parameter	Symbol	Conditions		Min.	Typi- cal	Maxi- mum	Units
Reverse Stand-Off Voltage	$V_{_{\mathrm{RWM}}}$	Pin 1 to 2 or 2 to 1				5	V
Reverse Breakdown Voltage	V_{BR}	I _t = 1mA Pin 1 to 2 or 2 to 1 T=-40°C to +125°C		6	8	10	V
Doverso Leakage Current		V _{RWM} = 5V, Pin 1 to 2 or 2 to 1	T=25°C		0.025	1	μΑ
Reverse Leakage Current	I _R		T=125°C			1	
Clamping Voltage	V _c	$I_{pp} = 1A, t_p = 8/20 \mu s$ Pin 1 to 2 or 2 to 1				11	V
Clamping Voltage	V _c	$I_{pp} = 12A, t_p = 8/20\mu s$ Pin 1 to 2 or 2 to 1				14	V
Junction Capacitance		$V_R = OV, f = 1MHz$	T=25°C			75	
		Pin 1 to 2 or 2 to 1	T=125°C			75	pF



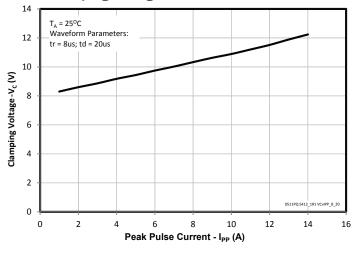
Typical Characteristics

Non-Boundation Books Books Books Books

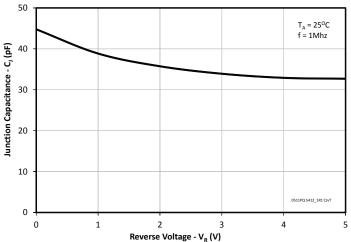




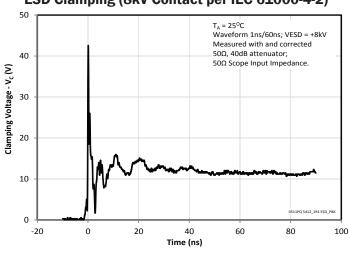
Clamping Voltage vs. Peak Pulse Current



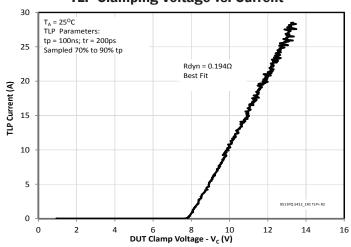




ESD Clamping (8kV Contact per IEC 61000-4-2)



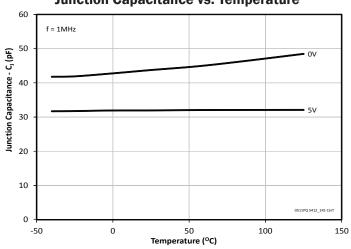
TLP Clamping Voltage vs. Current

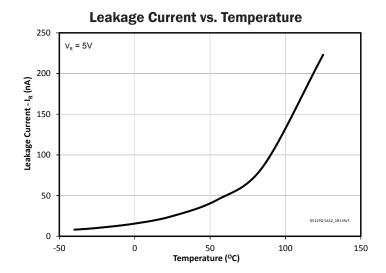




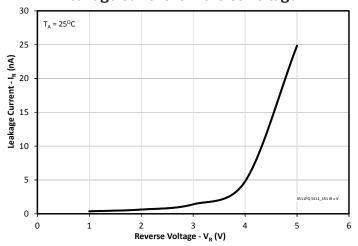
Typical Characteristics (Continued)

Junction Capacitance vs. Temperature

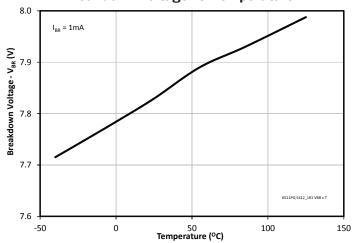




Leakage Current vs. Reverse Voltage



Breakdown Voltage vs. Temperature





Applications Information

Device Connection Options

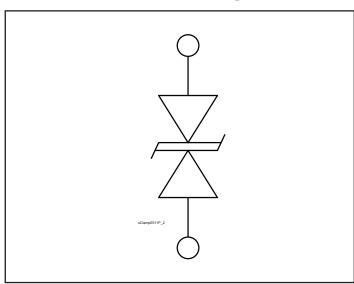
These TVS diodes are designed to protect one data, I/O, or power supply line. The device is bidirectional and may be used on lines where the signal polarity can go above and below ground.

Circuit Board Layout Recommendations for Suppression of ESD.

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Equivalent Circuit Diagram





Applications Information - Spice Model

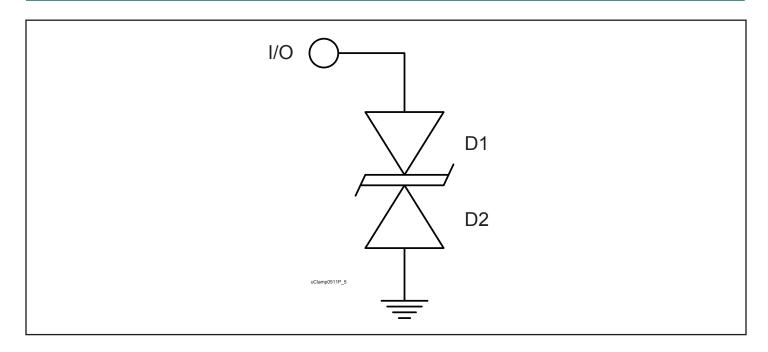
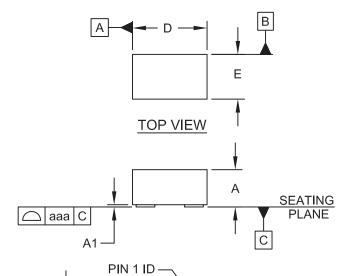


Figure 1 - uClamp0511PQ Spice Model

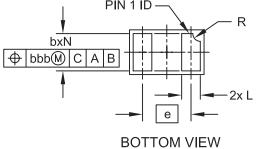
Table 1 - µClamp0511PQ Spice Parameters						
Parameter	Unit	D1 (TVS)	D2 (TVS)			
IS	Amp	1.48E-14	1.48E-14			
BV	Volt	7.3	7.3			
٧J	Volt	0.7	0.7			
RS	Ohm	0.157	0.157			
IBV	Amp	1E-3	1E-3			
CJO	Farad	85E-12	85E-12			
TT	sec	2.541E-9	2.541E-9			
M		0.126	0.126			
N		1.1	1.1			
EG	eV	1.11	1.11			



Outline Drawing - SLP1006P2



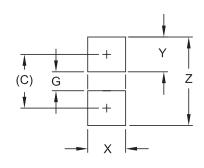
DIMENSIONS						
DIM	INCHES			MILLIMETERS		
וויווטן	MIN	MOM	MAX	MIN	MOM	MAX
Α	.016	.020	.022	0.40	0.50	0.55
A1	.000	.001	.002	0.00	0.03	0.05
b	.018	.020	.022	0.45	0.50	0.55
D	.035	.039	.043	0.90	1.00	1.10
E	.020	.024	.028	0.50	0.60	0.70
е	.026 BSC			0.65 BSC		
L	.008	.010	.012	0.20	0.25	0.30
R	.002	.004	.006	0.05	0.10	0.15
Ν	2			2		
aaa	.003		0.08			
bbb	.004			0.10		
LNIS-66YP35 R3						



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP1006P2



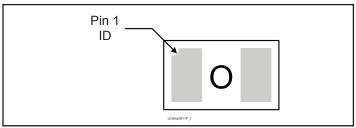
DIMENSIONS				
DIM	INCHES	MILLIMETERS		
С	(.033)	(0.85)		
G	.012	0.30		
Х	.024	0.60		
Υ	.022	0.55		
Ζ	.055	1.40		
		LNIS-66YP35 R3		

NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.



Marking



Notes:

1) Device is electrically symmetrical

Ordering Information

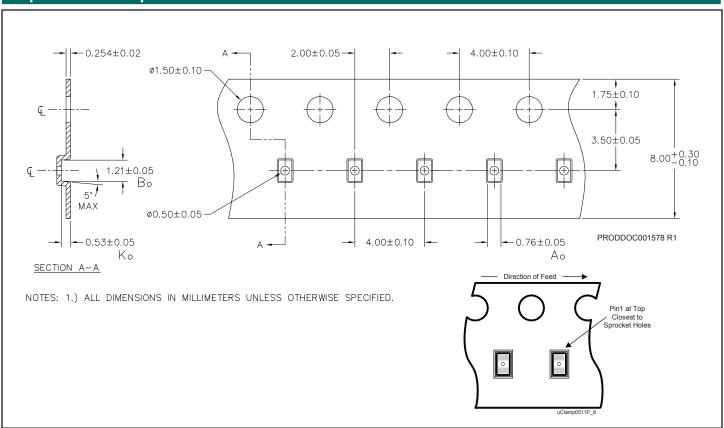
Part Number	Qty per Reel	Reel Size
uClamp0511PQTCT	3,000	7 Inch

Note: Lead finish is lead-free NiPdAu.

MicroClamp, uClamp and $\;\mu \text{Clamp}$ are marks of Semtech

Corporation.

Tape and Reel Specification



Contact Information

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